


APPLICATION DATA SHEET

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Title of Invention	[STACK-TYPE MULTI-CHIP PACKAGE AND METHOD OF FABRICATING BUMPS ON THE BACKSIDE OF A CHIP]	
Application Type : regular, utility Attorney Docket Number : 10544-US-PA		
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Priority Data: Doc.No: 92109018; Country -TW ; Date: 2003-04-18 us-priority-claimed		
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